



[54] MASKLESS METHOD FOR FABRICATING A LOW-LOSS MICROWAVE POWER SENSOR DEVICE

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[57] ABSTRACT

A method for forming a single cavity in a substrate, which may extend approximately the length of a device located on top of the substrate, and device produced thereby. The device has a length and a width, and may extend approximately the length of the substrate. After locating the device on the surface of the substrate, a first etchant is applied through openings on the surface of the substrate. Subsequently, a second etchant is applied through the same openings on the surface of the substrate. As a result, a single cavity is formed beneath the surface of the device, suspending the device and minimizing electrical coupling.

6 Claims, 8 Drawing Sheets

